



<b>Title of Change:</b>	Update Notice of IPCN20626XF1 to modify the qualification plan due to typo error.
<b>Proposed first ship date:</b>	14 December 2015
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or < Yasuhiro Igarashi @onsemi.com>
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or < Kazutoshi.Kitazume@onsemi.com>.
<b>Type of notification:</b>	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
<b>Change category:</b>	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____

<b>Change Sub-Category(s):</b>		<input type="checkbox"/> Datasheet/Product Doc change
<input type="checkbox"/> Manufacturing Site Change/Addition	<input checked="" type="checkbox"/> Material Change	<input type="checkbox"/> Shipping/Packaging/Marking
<input type="checkbox"/> Manufacturing Process Change	<input type="checkbox"/> Product specific change	<input type="checkbox"/> Other: _____

<b>Sites Affected:</b>		<input type="checkbox"/> External Foundry/Subcon site(s)
<input type="checkbox"/> All site(s)	<input type="checkbox"/> not applicable	<input checked="" type="checkbox"/> ON Semiconductor site(s) : ON Shenzhen, China

**Description and Purpose:**

IPCN20626XF is an Initial Process Change Notification to announce the contents below.

- 1) Changing wire material from gold to copper
- 2) Changing part number from XXXXXXX-TL-E, XXXXXXX-TL-H and XXXXXXX-TL-H-Z to XXXXXXX-TL-W and XXXXXXX-TL-W-Z.

PART_ID	New Part_ID
VEC2315-TL-H	VEC2315-TL-W
VEC2415-TL-E	VEC2415-TL-W
VEC2616-TL-H	VEC2616-TL-W
VEC2616-TL-H-Z	VEC2616-TL-W-Z

- 3) Changing mold compound from halide to halide free.

There's been a typo error in an issued IPCN as IPCN20626XF1, furthermore an error in Qualification Plan has been identified and another Update Notice is issued. The modification of test from "Steady State Operating Life" to "Intermittent Operating Life" and "Temp Humidity Storage" to "High Temperature High Humidity Reverse Bias" are been updated.

Test	Conditions	Read point
High Temperature High Humidity Reverse Bias	Ta=85degC, RH=85%, 80% V bias	1008 hrs.
High Temperature Reverse Bias	Ta=150degC, 80% V bias	1008 hrs.
High Temperature Gate Bias	Ta=150degC, 100% V bias	1008 hrs.
Temperature Cycle	Ta=-55degC to 150degC	500 cycles
Autoclave	Ta=121degC,RH=100%	96 hrs.
Intermittent Operating Life	Ta=25degC, delta Tj=100degC max	15000cycles
High Temperature Storage	Ta=150degC	1008 hrs.
Resistance to Soldering heat (Reflow)	Solder Temp.:260deg, 10s	

**List of Affected Standard Parts:**

- VEC2315-TL-H
- VEC2415-TL-E
- VEC2616-TL-H
- VEC2616-TL-H-Z